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**Universal Serial Bus interfaces for data and power –
Part 4-1: Universal Serial Bus 4™ Specification**

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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER

Part 4-1: Universal Serial Bus 4™ Specification

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The text of this International Standard is based on the following documents:

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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This standard is the USB-IF publication, USB4™ Specification, Version 1.0 with Errata and ECN through May 19, 2021.

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Universal Serial Bus 4 (USB4™) Specification

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Acknowledgement of Technical Contribution

The authors of this specification would like to recognize the following people who participated in the USB4 Specification technical work group.

Apple Inc. – Promoter Company Employees

Majd Abu Tayeh	Nimrod Agmon	Lior Aloni	Brian Baek
Omer Bar-Lev	Moshe Benyamini	Gopu Bhaskar	Carlos Calderon
David Conroy	Bill Cornelius	Scott Deandrea	William Ferry
Amit Flanter	Itay Franko	Radia Gantous	Alex Gerber
Mark Goikhman	Nir Guetta	Yair Hershkovitz	Scott Jackson
Husam Khashiboun	Alan Kobayashi	Alexei Kosut	Christine Krause
Dmitri Krichevsky	Alex Lozovik	Rachel Menes	Shlomi Mor
Shlomi Museri	Mona Omari	Tal Ostro	Arie Peled
Collin Pieper	Idan Reller	Reese Schreiber	Oleg Schtofenmaher
Etan Shirron	Ori Moshe Stern	Jose Tierno	Maxim Tsudik
Anatoly Uskach	Jeff Wilcox	Dan Wilson	Ohad Zalcman

HP Inc. – Promoter Company Employees

Roger Benson	Marcus Benzel	Alan Berkema	Kenneth Chan
Frank Chen	Phil Chen	Hosup Chung	Glen Dower
Mark Lessman	Nam Nguyen	Roger Pearson	Kenneth Smith
Chris Tabarez			

Intel Corporation – Promoter Company Employees

Nausheen Ansari	Noam Arzy	Alexandre Audier	Binata Bhattacharyya
Huimin Chen	Hengju Cheng	Salauddin Choudhury	John Crouter
Maxim Dan	Jhuda Dayan	Yoni Dishon	Eran Galil
Saranya Gopal	Venkataramani Gopalakrishnan	Raul Gutierrez	Michael Gouzenfeld
Mickey Gutman	Benjamin Hacker	Yaniv Hayat	Uri Hermoni
Alon Horn	Abdul Ismail	Abhilash K V	Ziv Kabiry
Vijaykumar Kadgi	Vijay Kasturi	Sergey Khaykin	Lev Kolomiets
Vladislav Kopzon	Efraim Kugman	Edmond Lau	Uriel Lemberger
Yun Ling	Guobin Liu	Balaji Manoharan	Liran Manor
Uma Medepalli	Assaf Mevorach	Hezi Naaman	Ohad Navon
Naod Negussie	CheeLim Nge	Leonid Plaks	Duane Quiet
Rajaram Regupathy	Reuven Rozic	Oren Salomon	Zeeshan Sarwar
Brad Saunders	Leonid Shaposhnik	Ehud Shoor	Ari Sharon

Uri Soloveychik	Einat Surijan	Aviel Uzan	Karthi Vadivelu
Alex Vekker	Chen Vrubel	Stephanie Wallick	Tzewen Wang
Sarel Wechsler	Ady Weiss	Vitaly Zhivov	Gal Yedidia
Vladimir Yudovich	Aruni Nelson		

Microsoft Corporation – Promoter Company Employees

Randy Aull	Jim Belesiu	Martin Borve	Anthony Chen
Jesse Chen	Matt Chung	Aacer Daken	Rajib Dutta
Mark Friend	Philip Froese	David Hargrove	Robbie Harris
Kit Hui	Toby Nixon	Rahul Ramadas	Andrea Severson
Kiran Shastry	Nathan Sherman	Ji Sun	Shyamal Varma

Renesas Corporation – Promoter Company Employees

Tam Do	Robert Dunstan	Philip Leung	Kiichi Muto
Ziba Nami	Hajime Nozaki	Raman Sargis	Yoshiyuki Tomoda
Starry Tsai	Jia Wei	Toshifumi Yamaoka	

STMicroelectronics – Promoter Company Employees

Nathalie Ballot	Joel Huloux	Gerard Mas	
-----------------	-------------	------------	--

Texas Instruments – Promoter Company Employees

Mike Campbell	Anant Gole	Craig Greenburg	Michael Koltun IV
Sai Karthik Rajaraman	Anwar Sadat	Cory Stewart	Sue Vining
Deric Waters	Gregory Watkins		

Contributor Company Employees

ACON, Advanced-Connectek, Inc.	Victory Chen	Conrad Choy	Vicky Chuang
	Jessica Feng	Sharon Hsiao	Wayne Wang
Advanced Micro Devices	Dennis Au	Nat Barbiero	Jason Chang
	Michael Comai	Walter Fry	Will Harris
	Jason Hawken	Jim Hunkins	Ling Kong
	Scott Ogle	Victor Salim	Joseph Scanlon
	Peter Teng		
Allion Labs, Inc.	Howard Chang	Casper Lee	Brian Shih
Analogix Semiconductor, Inc.	Greg Stewart	Haijian Sui	Yueke Tang
	Ning Zhu		
Anritsu Corporation	Wataru Aoba	John Jerico Custodio	Kazuhiro Fujinuma

	Hiroshi Goto	Alessandro Messina	Tadanori Nishikobara
	Ryo Sunayama	Toshihiro Suzuki	Mitsuhiro Usuba
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ASMedia Technology Inc.	Chang Chinyu	Chang Weiyun	Chen Chiahsin
	Chen Chunhung	Chuang Weber	Kuo Han Sung
	Lin Curtis	Lin ShuYu	Tseng PS
	Tseng YD	Wei Daniel	Wu ShengChung
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	Gaurav Jain	Poonam Khatri	Yash Kothari
	Vinod Lakshman	Shivaji Magadum	Andy Mauffet-Smith
	Rohit Mishra	Uyen Nguyen	Raja Pounraj
	Thirumal Reddy	Anand RK	Anshul Shah
	Neelabh Singh	Ofer Steinberg	Mark Summers
	Claire Ying	Wasiq Zia	
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Corning Optical Communications LLC	Mark Bradley	Wojciech Giziewicz	Ian McKay
	Jamie Silva		
Cypress Semiconductor	Mark Fu	Naman Jain	Savan Javia
	Palani Subbiah		
Dell Inc.	Mohammed Hijazi	Tom Lanzoni	Ken Nicholas
	Marcin Nowak	Scott Ogle	Adie Tan
	Lee Zaretsky		
Diodes Incorporated	Qun Song		
DisplayLink (UK) Ltd.	Pete Burgers	Dan Ellis	
DJI Technology Co., Ltd.	Steve Huang		
Electronics Testing Center, Taiwan	Sophia Liu		
Elka International Ltd.	Alvin Cheng	Chloe Hsieh	Roy Ting

	Jui-Ming Yang		
Ellisys	Abel Astley	Mario Pasquali	Chuck Trefts
	Tim Wei		
Etron Technology, Inc.	Andy Chen	Shihmin Hsu	Bryan Huang
	Chien-Cheng Kuo	Jen Hong Larn	
Foxconn / Hon Hai	Patrick Casher	Joe Chen	Jason Chou
	Fred Fons	Bob Hall	Terry Little
	Christine Tran	A.J. Yang	Jie Zheng
Fresco Logic Inc.	Tim Barilovits	Bob McVay	Christopher Meyers
	Jie Ni	Jeffrey Yang	
Genesys Logic, Inc.	Sean Chen	Gerry Chou	Thomas Hsieh
	Jerry Hu	Perlman Hu	Roy Huang
	ChunYen Kuo	Weddell Lee	Jimmy Lin
	Miller Lin	D.C. Lu	Greg Tu
	Han Wu	Yihsun Wu	
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	David Schneider		
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	Alan Chuang	Steven Lee	Caspar Lin
	Tim Lin	Krishna Murthy	Johnson Tan
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	Andrew Stewart	Mark Vennebarger	
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	Tyler Joe	Carlo Mazzetti	Mike Micheletti
	Kathryn Morales	Jeff Sabuda	Joseph Schachner
	Chris Webb		
Lenovo	Toshikazu Horino	Shinji Matsushima	Yuuki Matsuura
	Nozomu Nagata	Munefumi Nakata	Kazuya Shibayama
	Shunki Sugai	Chikara Takahashi	Masahiro Tokuno
	Kayanagi Tsuneo		
LG Electronics Inc.	Do Kyun Kim	Yoon Jong Lee	Seung Yoo
Lintes Technology Co., Ltd.	Tammy Huang	Charles Kaun	RD Lintes
	Max Lo	CT Pien	Jin Yi Tu
	Jason Yang		
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MediaTek Inc.	Henry Chen	Alexyc Lin	Pochou Lin
	Chiachun Wang		
MegaChips Corporation	Rahul Agarwal	Ramesh Dandapani	Satoru Kumashiro
	Ryuichi Mariizumi	Sireesha Vemulapalli	Nobu Yanagisawa
Mercedes-Benz Research & Development, North America, Inc.	Hans Wickler		
Microchip Technology Inc.	Mark Bohm	Atish Ghosh	Fernando Gonzalez
	Mark Gordon	Richard Petrie	Brigham Steele
	Anthony Tarascio	Robert Zakowicz	
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Newnex Technology Corp.	Sam Liu		
NVIDIA	Jamie Aitken	Mark Overby	
NXP Semiconductors	Mahmoud El Sabbagh	Ken Jaramillo	Abhijeet Kulkarni
	Vijendra Kuroodi	Krishnan TN	
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	Amir Lahooti		
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	Soren Petersen		
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	Ho Wen Tsai	Eric Wu	Randolph Wu
	Simon Yeh		
Western Digital	David Landsman	Larry McMillan	Rob Ryan
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	Majid Shayegh		

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1 Introduction

1.1 Scope of the Document

The specification is primarily targeted at peripheral developers and platform/adaptor developers, but provides valuable information for platform operating system/BIOS/device driver, adaptor independent hardware vendors/independent software vendors, and system OEMs. This specification can be used for developing new products and associated software.

1.2 USB Product Compliance

Adopters of the USB4™ specification have signed the USB4 Adopters Agreement, which provides them access to a royalty-free reasonable and nondiscriminatory (RAND) license from the Promoters and other Adopters to certain intellectual property contained in products that are compliant with the USB4 specification. Adopters can demonstrate compliance with the specification through the testing program as defined by the USB Implementers Forum (USB-IF). Products that demonstrate compliance with the specification will be granted certain rights to use the USB-IF logos as defined in the logo license.

1.3 Document Organization

Chapters 1 and 2 provide an overview for all readers, while Chapters 3 through 13 contain detailed technical information defining USB4.

1.4 Design Goals

USB 3.1 and USB 3.2 were evolutionary steps to increase bandwidth. The goal for USB4 remains the same with the added goal of helping to converge the USB Type-C® connector ecosystem and minimize end-user confusion. Several key design areas to meet this goal are listed below:

- Offer display, data, and load/store functionality over a single USB Type-C connector.
- Retain compatibility with existing ecosystem of USB and Thunderbolt™ products.
- Define Port Capabilities for predictable and consistent user experience.
- Provide increased host flexibility to configure bandwidth, power management, and other performance-related parameters for system needs.

1.5 Related Documents

Universal Serial Bus 3.2 Specification, Revision 1.0, September 22, 2017 (USB 3.2 Specification)

USB Type-C® Cable and Connector Specification, Release 2.0 (USB Type-C Specification)

USB 3.0 Jitter Budgeting white paper (USB Jitter Paper)

Universal Serial Bus Power Delivery Specification, Release 3.0, Version 2.0, August 2019 (USB PD Specification)

PCI Express® Base Specification, Revision 4, Version 1, September 27, 2017 (PCIe Specification)

VESA DisplayPort™ Standard, Revision 1.2a, May 2012 (DisplayPort 1.2a Specification)

VESA DisplayPort™ Standard, Revision 1.4a, April 19, 2018 (DisplayPort 1.4a Specification)

VESA DisplayPort™ 1.4a PHY Layer Compliance Test Specification, Revision 1.0, 27 July, 2018 (DisplayPort 1.4a PHY CTS)

VESA DisplayPort™ Alt Mode on USB Type-C Standard, Revision 1.0b, November 03, 2017 (DisplayPort Alt Mode Specification)

eXtensible Host Controller Interface for Universal Serial Bus, Revision 1.1 (xHCI Specification)

USB4 Connection Manager (CM) Guide, Revision 1.0, [to be published] – (Connection Manager Guide)

USB4 Re-Timer Specification, [to be published] – (USB4 Re-Timer Specification)

USB4 Device ROM (DROM) Specification, Revision 1.0, [to be published] – (USB4 DROM Specification)

USB4 Inter-Domain Specification, Revision 1.0, [to be published] – (USB4 Inter-Domain Specification)

HDCP on DisplayPort™ Specification, Revision 2.3, January 22, 2019 (HDCP Specification)